

AMENDMENT UNDER 37 C.F.R. § 1.111  
U.S. Appln. No. 09/719,422

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3. (Twice Amended) A pressure-sensitive adhesive tape, which can be used in the resin encapsulating method for a semiconductor chip according to claim 1 or 2 and has a thermal shrinkage of 3% or less on resin encapsulating and a pressure-sensitive adhesive strength of 400 gf/20 mm or less at 23°C after the adhesive tape being heated at 180°C.

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